

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jing-En LUAN	10/30/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	STMicroelectronics Asia Pacific Pte Ltd.
<b>Street Address:</b>	5A, Serangoon North Avenue 5
<b>City:</b>	Singapore
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	554574
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12938235
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(303)899-7333
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	719-448-5947
<b>Email:</b>	julie.lange@hoganlovells.com
<b>Correspondent Name:</b>	HOGAN LOVELLS US LLP
<b>Address Line 1:</b>	ONE TABOR CENTER, SUITE 1500
<b>Address Line 2:</b>	1200 SEVENTEENTH ST
<b>Address Line 4:</b>	DENVER, COLORADO 80202
<b>ATTORNEY DOCKET NUMBER:</b>	09-TPY-005
<b>NAME OF SUBMITTER:</b>	Scott J. Hawranek
<b>Total Attachments: 3</b> source=DOC141#page1.tif source=DOC141#page2.tif source=DOC141#page3.tif	

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PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Jing-En LUAN Execution Date: 10/30/2010

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

STMicroelectronics Asia Pacific Pte Ltd.  
5A, Serangoon North Avenue 5  
Singapore 554574  
SINGAPORE

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance

- Assignment  Merger
- Security Agreement  Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other \_\_\_\_\_

4. Application or patent number(s):

A. Patent Application No.(s)  
Attorney Docket No.: 09-TPY-005

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and Address to whom correspondence concerning document should be mailed:

Name: William J. Kubida  
Internal Address: Hogan Lovells US LLP  
One Tabor Center  
1200 17th Street, Suite 1500  
Street Address: same as above  
City: Denver State: CO Zip: 80202  
Phone Number: 719-448-5909  
Fax Number: 719-448-5922  
Email Address: PatentColorado@hhlaw.com

6. Total number of applications and patents involved: 1

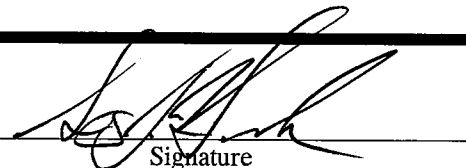
7. Total fee (37 CFR 1.21(h) & 3.41)..... \$ 40.00

- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

Deposit account number 50-1123  
Authorized User Name \_\_\_\_\_

9. Signature :

  
Signature

11/1/2010  
Date

**Scott J. Hawranek**  
Name of Person signing

Total number of pages including cover sheet, attachments and document: 3

**ASSIGNMENT**

WHEREAS, I, Jing-En LUAN, having a residence address of Blk 538 #02-4014, Ang Mo Kio Ave. 5, 560538 Singapore, have made a certain new and useful invention relating to a **LOW PROFILE CHIP SCALE MODULE AND METHOD OF PRODUCING THE SAME**, for which I am making or have made application for Letters Patent of the United States, said application being identified by Docket No. 09-TPY-005 and Client/Matter No. 80408.0254, in the law firm of HOGAN LOVELLS US LLP, One Tabor Center, 1200 17th Street, Suite 1500, Denver, Colorado 80202, and which was executed on 30 October 2010 and assigned serial no. 12/938,235;

WHEREAS, I now own the entire right, title and interest therein; and

WHEREAS, STMicroelectronics Asia Pacific Pte Ltd., hereinafter ASSIGNEE, whose post office address is 5A, Serangoon North Avenue 5, Singapore 554574, SINGAPORE, is desirous of acquiring the entire interest in and to said invention, said application, and the Letters Patent to be obtained therefor.

NOW THEREFORE, upon consideration of my employment and other good and valuable consideration, the adequacy of which is hereby acknowledged, I do hereby sell and assign unto ASSIGNEE, and ASSIGNEE's legal representatives, successors, and assigns, the entire right, title, and interest in and to said invention, said application, and the Letters Patent, both of the United States and of other countries, that may or shall issue thereon; and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to ASSIGNEE, consistent with the terms of this Assignment.

UPON SAID CONSIDERATION, I do hereby covenant and agree with ASSIGNEE that I will not execute any writing or do any act whatsoever conflicting with this assignment, and that I will, at any time upon request, without further or additional consideration, but at the expense of ASSIGNEE, execute such additional assignments and other writings and do such additional acts as ASSIGNEE may deem necessary or desirable to perfect the ASSIGNEE's enjoyment of this grant, and render all necessary assistance in applying for and obtaining original, continuation, continuation-in-part, divisional, reexamined, renewal, reissued or extended Letters Patent of the


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United States, or of other countries, or inventor's certificates, on said invention, and in enforcing any rights or causes in action accruing as a result of such applications, certificates, or patents, by giving testimony in any proceedings or transactions involving such applications, certificates, or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of both parties.

The undersigned inventor hereby grants the patent practitioners associated with Customer No. 30429 the power to insert in this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, I have hereunto set my hand and affixed my seal on the date hereinafter set forth.

Date: 7/21/10

  
\_\_\_\_\_  
Jing-En LUAN